Appendix 3 Product End-of-Life Disassembly instructions

Product Identification:

<table>
<thead>
<tr>
<th>Marketing Name / Model</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>Compaq Presario M2000 Series Notebook PC</td>
<td>Notebook PC</td>
</tr>
</tbody>
</table>

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 square cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>1</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 square cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB / PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td>Declaration limited to case plastics only.</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>Type-cross #1 (JIS B 4633-1987)</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

<table>
<thead>
<tr>
<th>Step</th>
<th>Action</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Remove 6 or 12 cell main battery from system bottom.</td>
</tr>
<tr>
<td>2</td>
<td>Remove two M2.5*5L screws on HDD door, then remove HDD.</td>
</tr>
<tr>
<td>3</td>
<td>Remove a M2.5*6L screw on BASE cover, then remove ODD.</td>
</tr>
<tr>
<td>4</td>
<td>Remove three M2.5*5L screws on BASE cover, then remove RAM door and MINIPCI door.</td>
</tr>
<tr>
<td>5</td>
<td>Remove two M2.5*4L screws to remove the keyboard cover.</td>
</tr>
<tr>
<td>6</td>
<td>Remove three M2.5<em>3L and one M2.5</em>6L screws to remove the keyboard and release out the T/P module FFC.</td>
</tr>
<tr>
<td>7</td>
<td>Remove two M2.5*6L screws to remove the led board.</td>
</tr>
<tr>
<td>8</td>
<td>Remove four M2.5*6L screws, then remove LCD assy.</td>
</tr>
<tr>
<td>9</td>
<td>Remove five M2.5<em>6L, three M2.5</em>4L screws on top side and seven M2.5<em>6L, five M2.5</em>15L, six M2.5*4L screws on bottom side to remove base cover and speaker box.</td>
</tr>
<tr>
<td>10</td>
<td>Remove two M2.5*4L screw and then remove daughter board.</td>
</tr>
<tr>
<td>11</td>
<td>Remove two M2.5*4L screws and then remove the battery board.</td>
</tr>
<tr>
<td>12</td>
<td>Remove two M2.5*4L screws and then remove the DC board.</td>
</tr>
<tr>
<td>13</td>
<td>Remove three M2.5*4L screws and then remove MB</td>
</tr>
<tr>
<td>14</td>
<td>Remove four M2.0 spring screw and one M2.5*4L screw and then remove thermal module.</td>
</tr>
<tr>
<td>15</td>
<td>Remove six M2.5*5L screws and then remove LCD bezel.</td>
</tr>
<tr>
<td>16</td>
<td>Remove six M2.5<em>5L and four M2</em>3L screws to remove LCD panel and inverter board.</td>
</tr>
<tr>
<td>17</td>
<td>Divide from connecter and remove RTC coin cell battery on MB for selective treatment</td>
</tr>
<tr>
<td>18</td>
<td>Disassemble LCD panel and remove mercury bulb for selective treatment.</td>
</tr>
</tbody>
</table>
3.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below: